



### Product Summary

V <sub>(BR)DSS</sub>	R <sub>DS(on)TYP</sub>	I <sub>D</sub>
-20V	68mΩ@-4.5V	-2.3A
	95mΩ@-2.5V	
20V	32mΩ@4.5V	3.5A
	49mΩ@2.5V	

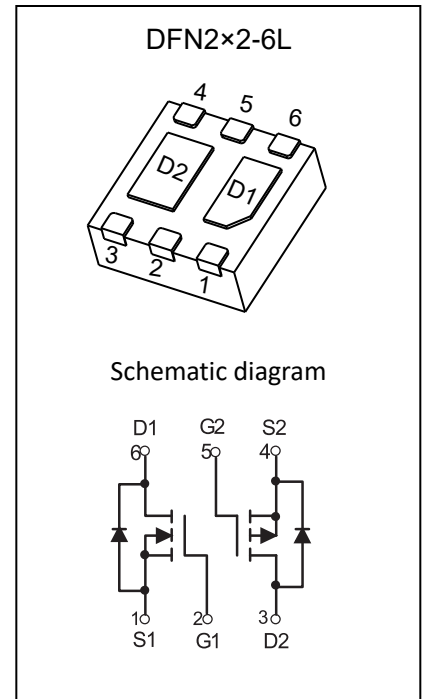
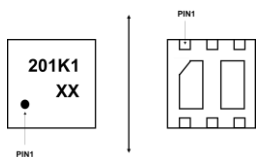
### Feature

- TrenchFET Power MOSFET
- High Density Cell Design for Low R<sub>DS(ON)</sub>
- Voltage Controlled Small Signal Switch

### Application

- Load Switch for Portable Devices
- DC/DC Converter

### MARKING:



### ABSOLUTE MAXIMUM RATINGS (T<sub>a</sub>=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
<b>P-MOSFET</b>			
Drain-Source Voltage	V <sub>DS</sub>	-20	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Continuous Drain Current	I <sub>D</sub>	-2.3	A
Pulsed Drain Current <sup>(1)</sup>	I <sub>DM</sub>	-9	A
Power Dissipation	P <sub>D</sub>	0.75	W
<b>N-MOSFET</b>			
Drain-Source Voltage	V <sub>DS</sub>	20	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Continuous Drain Current	I <sub>D</sub>	3.5	A
Pulsed Drain Current <sup>(1)</sup>	I <sub>DM</sub>	14	A
Power Dissipation	P <sub>D</sub>	0.75	W
<b>Temperature and Thermal Resistance</b>			
Thermal Resistance from Junction to Ambient <sup>(2)</sup>	R <sub>θJA</sub>	167	°C/W
Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature	T <sub>STG</sub>	-55~ +150	°C

## P-channel MOSFET ELECTRICAL CHARACTERISTICS ( $T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-20			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = -16V, V_{GS} = 0V$			-1	$\mu A$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 8V, V_{DS} = 0V$			$\pm 100$	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-0.4	-0.7	-1.0	V
Drain-source on-resistance <sup>(3)</sup>	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -2.8A$		68	110	m $\Omega$
		$V_{GS} = -2.5V, I_D = -2.0A$		95	140	
Forward transconductance	$g_{FS}$	$V_{DS} = -5V, I_D = -2.0A$	3			S
Diode forward voltage <sup>(3)</sup>	$V_{DS}$	$I_S = -0.7A, V_{GS} = 0V$			-1.2	V
<b>Dynamic characteristics<sup>(4)</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = -10V, V_{GS} = 0V, f = 1MHz$		363		pF
Output Capacitance	$C_{oss}$			70		
Reverse Transfer Capacitance	$C_{rss}$			60		
Total gate charge	$Q_g$	$V_{DS} = -10V, V_{GS} = -2.5V, I_D = -3A$		3.2		nC
Gate-source charge	$Q_{gs}$			0.6		
Gate-drain charge	$Q_{gd}$			1.2		
<b>Switching Characteristics<sup>(4)</sup></b>						
Turn-on delay time	$t_{d(on)}$	$V_{DD} = -10V, V_{GEN} = -4.5V, I_D = -1A$ $R_L = 10\Omega, R_{GEN} = 1\Omega$		9		nS
Turn-on rise time	$t_r$			33		
Turn-off delay time	$t_{d(off)}$			29		
Turn-off fall time	$t_f$			9		

## N-channel MOSFET ELECTRICAL CHARACTERISTICS ( $T_a=25^\circ\text{C}$ unless otherwise noted)

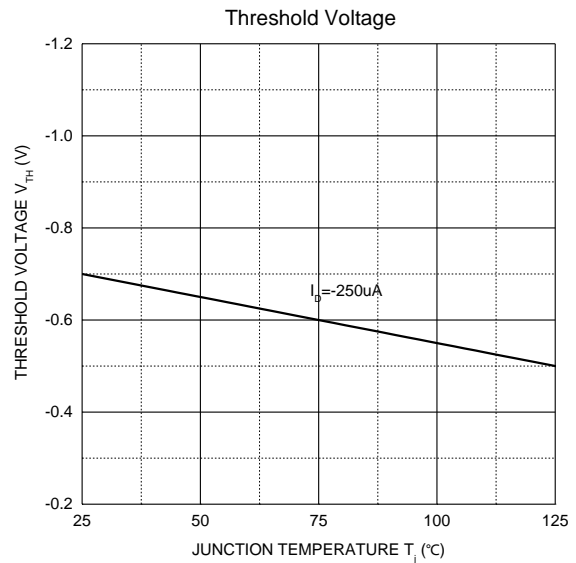
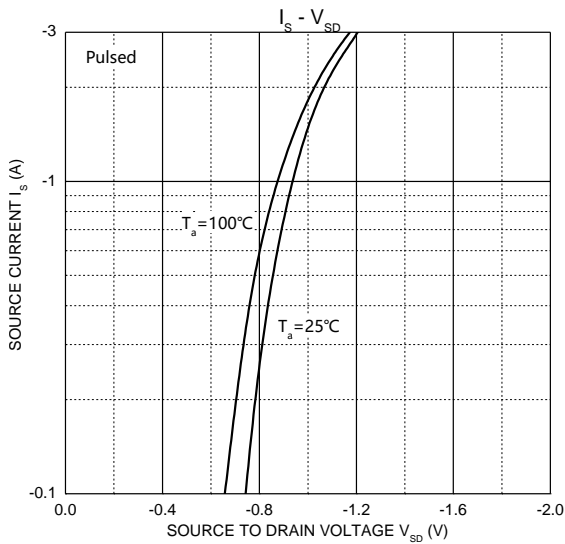
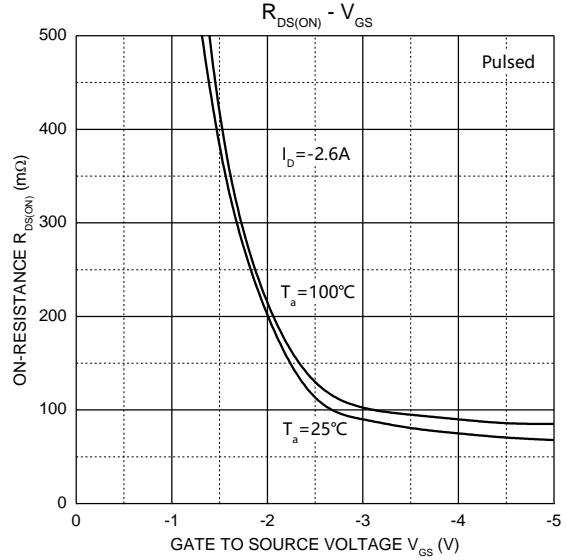
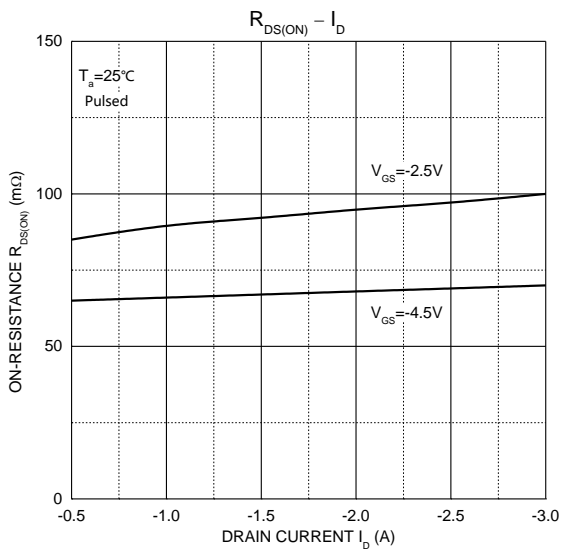
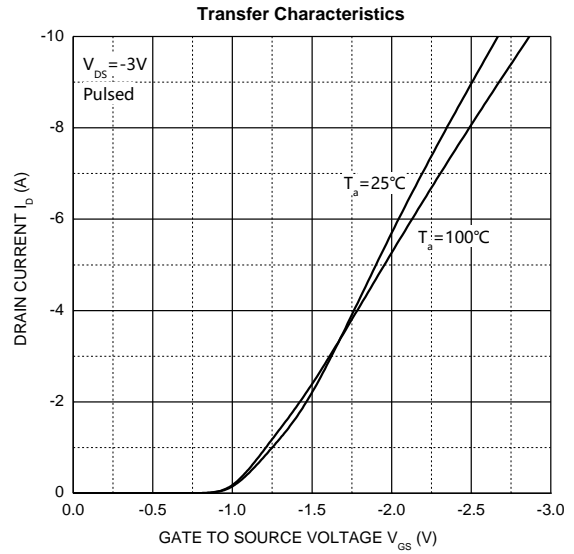
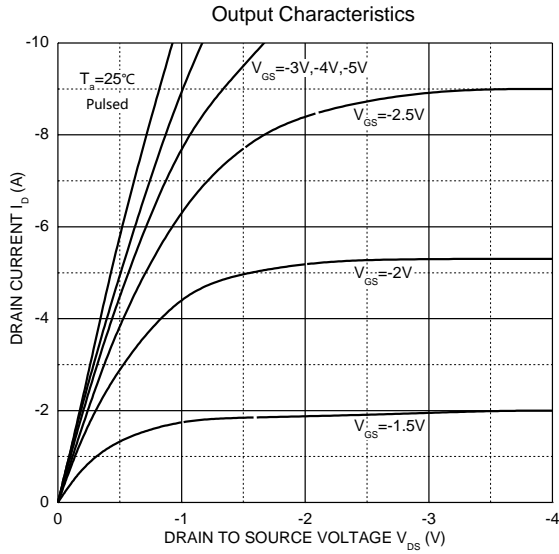
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	20			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 16V, V_{GS} = 0V$			1	$\mu A$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 8V, V_{DS} = 0V$			$\pm 100$	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.6	0.8	1.2	V
Drain-source on-resistance <sup>(3)</sup>	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 3.6A$		32	60	m $\Omega$
		$V_{GS} = 2.5V, I_D = 3.1A$		49	80	
Forward transconductance	$g_{FS}$	$V_{DS} = 5V, I_D = 3.6A$		8		S
Diode Forward voltage <sup>(3)</sup>	$V_{DS}$	$V_{GS} = 0V, I_S = 0.94A$			1.2	V
<b>Dynamic characteristics<sup>(4)</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 10V, V_{GS} = 0V, f = 1MHz$		260		pF
Output Capacitance	$C_{oss}$			48		
Reverse Transfer Capacitance	$C_{rss}$			27		
Total gate charge	$Q_g$	$V_{DS} = 10V, V_{GS} = 4.5V, I_D = 3.0A$		2.9	5	nC
Gate-source charge	$Q_{gs}$			0.4		
Gate-drain charge	$Q_{gd}$			0.6		
<b>Switching Characteristics<sup>(4)</sup></b>						
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 10V, R_L = 3.3\Omega, V_{GEN} = 4.5V, R_g = 6\Omega$		2.5		ns
Turn-on rise time	$t_r$			3.2		
Turn-off delay time	$t_{d(off)}$			21		
Turn-off fall time	$t_f$			3		

### Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t < 5$  sec.
3. Pulse Test : Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production testing.

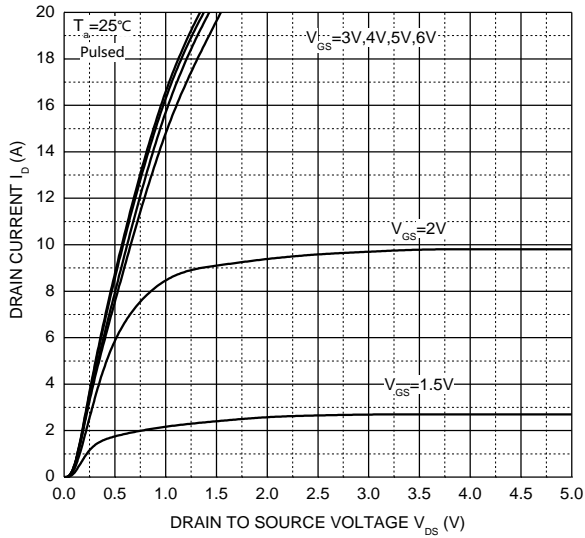
**Typical Electrical and Thermal Characteristics**

**P-Channel MOS**

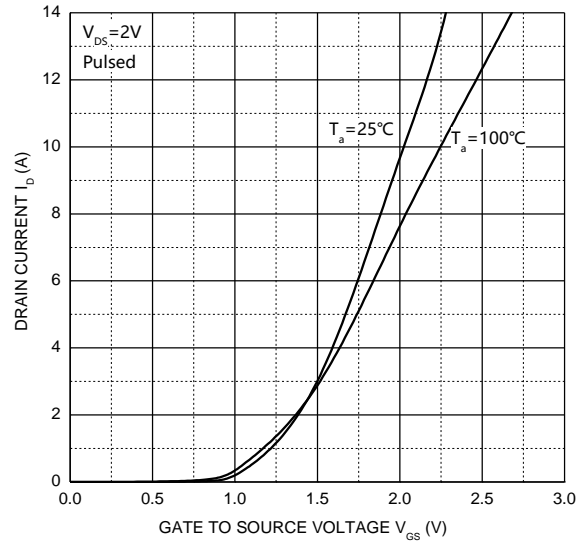


N-Channel MOS

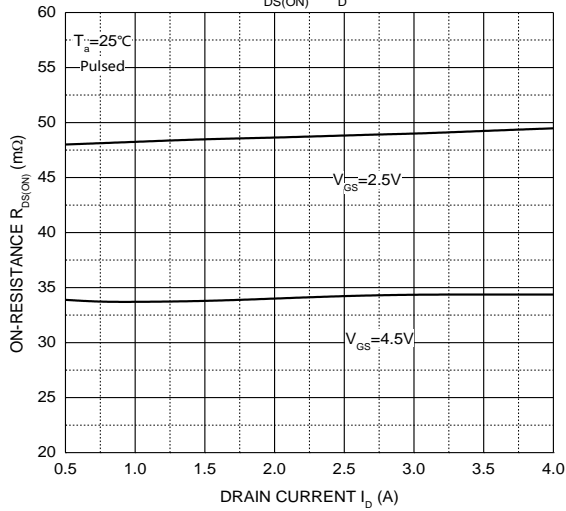
Output Characteristics



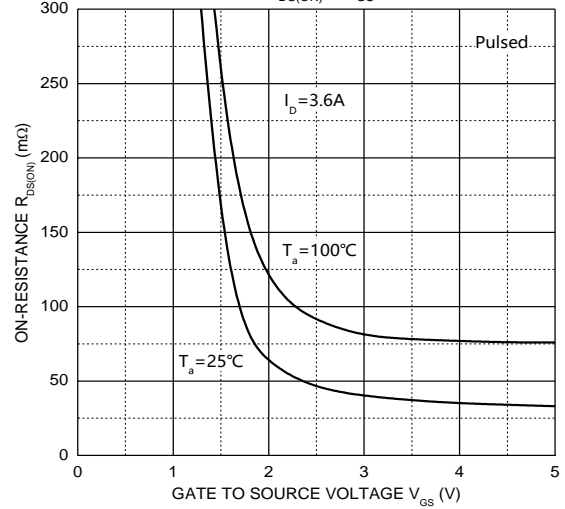
Transfer Characteristics



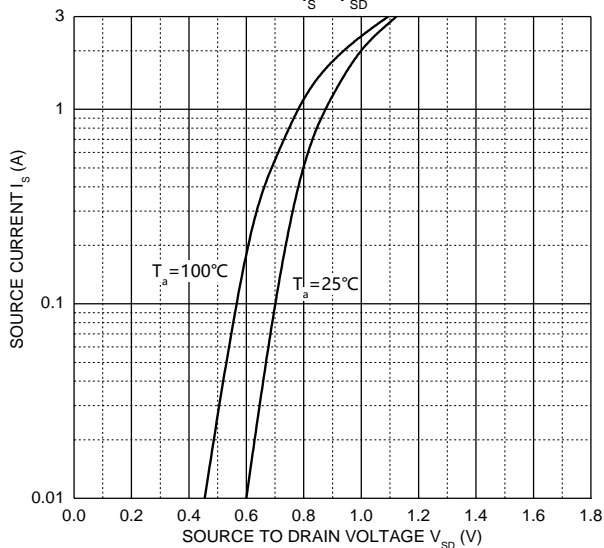
$R_{DS(ON)} - I_D$



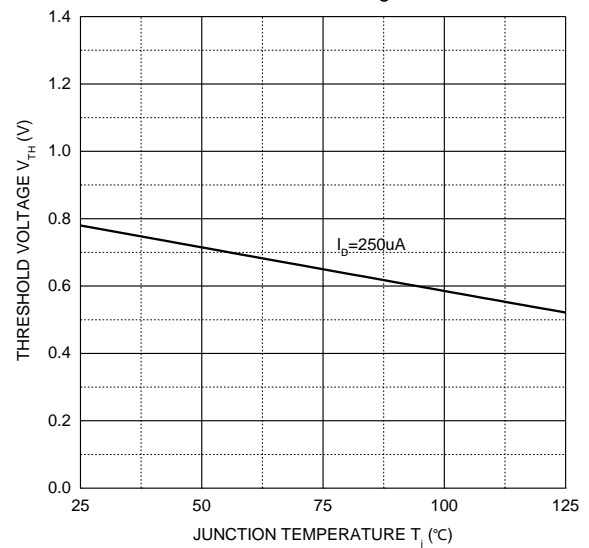
$R_{DS(ON)} - V_{GS}$



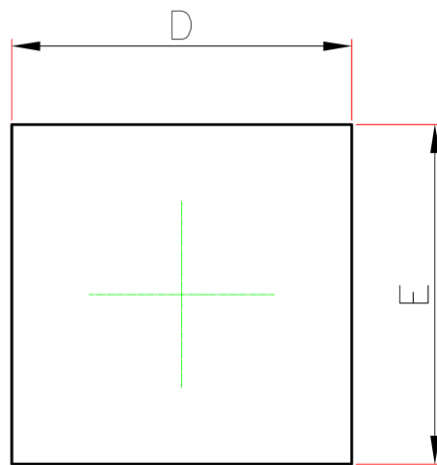
$I_S - V_{SD}$



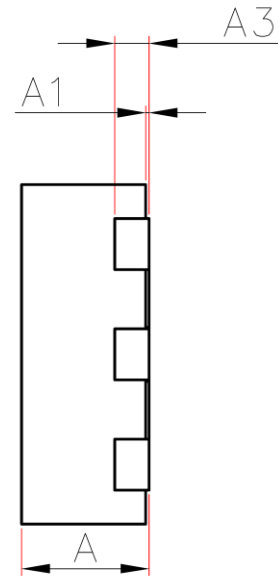
Threshold Voltage



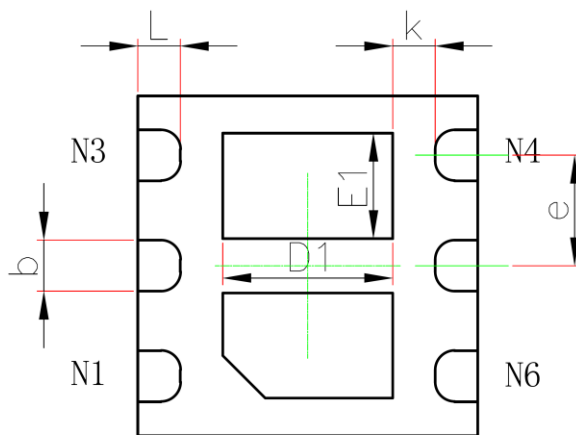
## DFN2x2-6L Package Information



TOP VIEW



SIDE VIEW



BOTTOM VIEW

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0	0.050	0	0.002
A3	2.03REF		0.008REF	
D	1.900	2.100	0.075	0.083
E	1.900	2.100	0.075	0.083
D1	0.900	1.100	0.035	0.043
E1	0.520	0.720	0.020	0.028
k	0.200MIN		0.008MIN	
b	0.250	0.350	0.010	0.014
e	0.65BSC		0.026TYP	
L	0.174	0.326	0.007	0.013